

# SN54ALS832A, SN54AS832B, SN74ALS832A, SN74AS832B HEX 2-INPUT OR DRIVERS

SDAS017C – DECEMBER 1982 – REVISED JANUARY 1995

- High Capacitive-Drive Capability
- 'ALS832A Has Typical Delay Time of 4.8 ns ( $C_L = 50$  pF) and Typical Power Dissipation of 4.5 mW Per Gate
- 'AS832B Has Typical Delay Time of 3.2 ns ( $C_L = 50$  pF) and Typical Power Dissipation of Less Than 13 mW Per Gate
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

## description

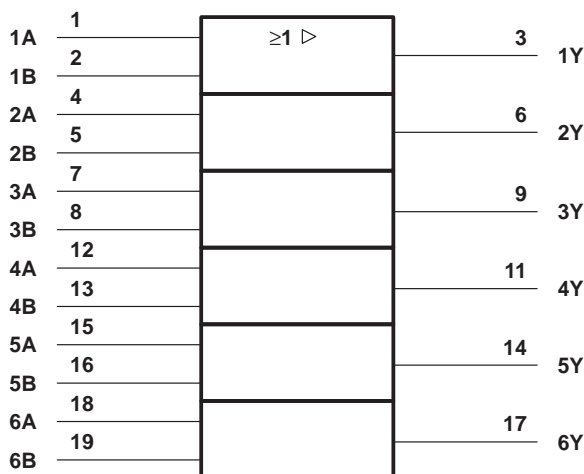
These devices contain six independent 2-input OR drivers. They perform the Boolean functions  $Y = A + B$  or  $Y = \overline{A} \cdot \overline{B}$  in positive logic.

The SN54ALS832A and SN54AS832B are characterized for operation over the full military temperature range of  $-55^\circ\text{C}$  to  $125^\circ\text{C}$ . The SN74ALS832A and SN74AS832B are characterized for operation from  $0^\circ\text{C}$  to  $70^\circ\text{C}$ .

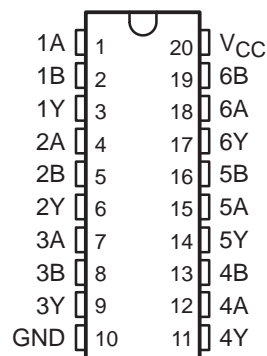
FUNCTION TABLE  
(each driver)

INPUTS		OUTPUT Y
A	B	
H	X	H
X	H	H
L	L	L

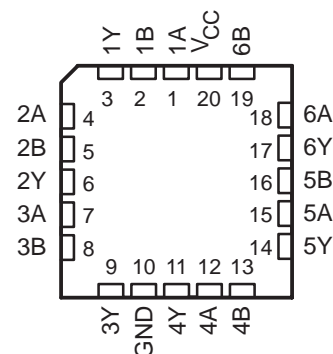
## logic symbol†



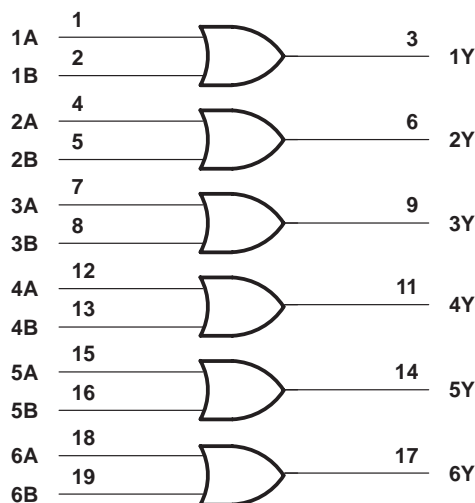
SN54ALS832A, SN54AS832B ... J PACKAGE  
SN74ALS832A, SN74AS832B ... DW OR N PACKAGE  
(TOP VIEW)



SN54ALS832A, SN54AS832B ... FK PACKAGE  
(TOP VIEW)



## logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# SN54ALS832A, SN54AS832B, SN74ALS832A, SN74AS832B HEX 2-INPUT OR DRIVERS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, $V_{CC}$	7 V
Input voltage, $V_I$	7 V
Operating free-air temperature range, $T_A$ : SN54ALS832A	–55°C to 125°C
SN74ALS832A	0°C to 70°C
Storage temperature range	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions

		SN54ALS832A			SN74ALS832A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.7			0.8	V
$I_{OH}$	High-level output current			–12			–15	mA
$I_{OL}$	Low-level output current			12			24	mA
$T_A$	Operating free-air temperature	–55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALS832A			SN74ALS832A			UNIT
			MIN	TYP <sup>‡</sup>	MAX	MIN	TYP <sup>‡</sup>	MAX	
$V_{IK}$	$V_{CC} = 4.5$ V,	$I_I = -18$ mA			–1.5			–1.5	V
$V_{OH}$	$V_{CC} = 4.5$ V to 5.5 V,	$I_{OH} = -0.4$ mA	$V_{CC} - 2$			$V_{CC} - 2$			V
	$V_{CC} = 4.5$ V	$I_{OH} = -3$ mA	2.4	3.2		2.4	3.2		
		$I_{OH} = -12$ mA	2						
		$I_{OH} = -15$ mA				2			
$V_{OL}$	$V_{CC} = 4.5$ V	$I_{OL} = 12$ mA		0.25	0.4		0.25	0.4	V
		$I_{OL} = 24$ mA					0.35	0.5	
$I_I$	$V_{CC} = 5.5$ V,	$V_I = 7$ V			0.1			0.1	mA
$I_{IH}$	$V_{CC} = 5.5$ V,	$V_I = 2.7$ V			20			20	μA
$I_{IL}$	$V_{CC} = 5.5$ V,	$V_I = 0.4$ V			–0.1			–0.1	mA
$I_{O}^{\S}$	$V_{CC} = 5.5$ V,	$V_O = 2.25$ V	–20		–112	–30		–112	mA
$I_{CCH}$	$V_{CC} = 5.5$ V,	$V_I = 4.5$ V		6	9		6	9	mA
$I_{CCL}$	$V_{CC} = 5.5$ V,	$V_I = 0$		9.5	16		9.5	16	mA

<sup>‡</sup> All typical values are at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$ .

<sup>\S</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .



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# SN54ALS832A, SN54AS832B, SN74ALS832A, SN74AS832B HEX 2-INPUT OR DRIVERS

SDAS017C – DECEMBER 1982 – REVISED JANUARY 1995

## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			SN54ALS832A		SN74ALS832A		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	1	13	2	9	ns
t <sub>PHL</sub>			1	11	1	8	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Operating free-air temperature range, T <sub>A</sub> : SN54AS832B	–55°C to 125°C
SN74AS832B	0°C to 70°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions§

		SN54AS832B			SN74AS832B			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
I <sub>OH</sub>	High-level output current			–40			–48	mA
I <sub>OL</sub>	Low-level output current			40			48	mA
T <sub>A</sub>	Operating free-air temperature	–55		125	0		70	°C

§ These high sink- or source-current devices are not recommended for use above 40 MHz.

# SN54ALS832A, SN54AS832B, SN74ALS832A, SN74AS832B HEX 2-INPUT OR DRIVERS

SDAS017C – DECEMBER 1982 – REVISED JANUARY 1995

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	SN54AS832B			SN74AS832B			UNIT
					MIN	TYP†	MAX	
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$	-1.2			-1.2			V
$V_{OH}$	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $I_{OH} = -2\text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$			2.4	3.2	2.4 3.2	
		$I_{OH} = -40\text{ mA}$			2			
		$I_{OH} = -48\text{ mA}$					2	
$V_{OL}$	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 40\text{ mA}$			0.25	0.5		V
		$I_{OL} = 48\text{ mA}$					0.35 0.5	
$I_I$	$V_{CC} = 5.5\text{ V}$ , $V_I = 7\text{ V}$	0.1			0.1			mA
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 2.7\text{ V}$	20			20			$\mu\text{A}$
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 0.4\text{ V}$	-0.5			-0.5			mA
$I_{O\ddagger}$	$V_{CC} = 5.5\text{ V}$ , $V_O = 2.25\text{ V}$	-50 -200			-50 -200			mA
$I_{CCH}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 4.5\text{ V}$	11 17			11 17			mA
$I_{CCL}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 0$	22 36			22 36			mA

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

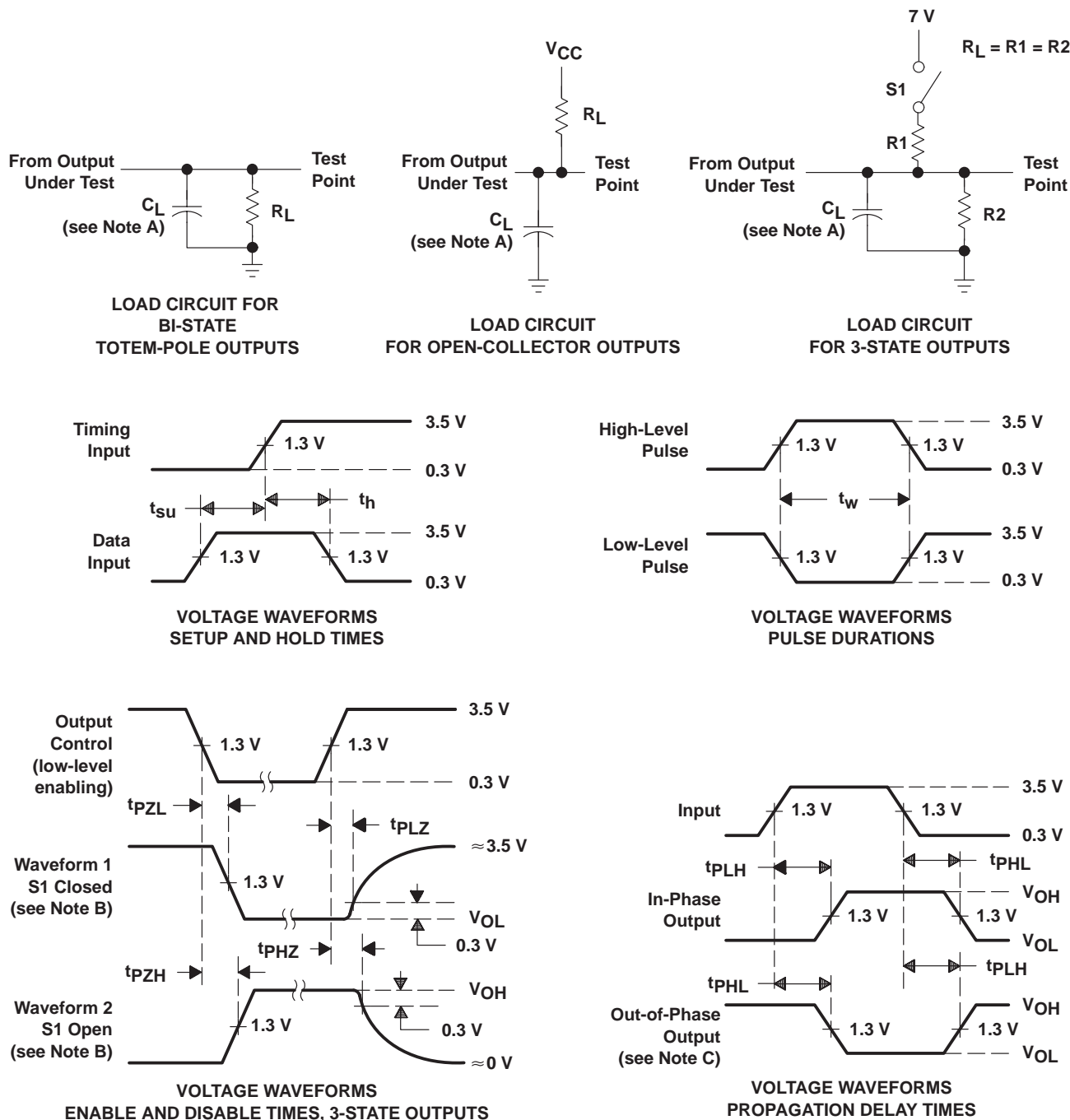
‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX§				UNIT
			SN54AS832B		SN74AS832B		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	1	7.5	1	6.3	ns
t <sub>PHL</sub>			1	7	1	6.3	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION  
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.  
D. All input pulses have the following characteristics:  $PRR \leq 1$  MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.  
E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-88523012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 88523012A SNJ54AS 832BFBK	<a href="#">Samples</a>
8414501RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8414501RA SNJ54ALS832AJ	<a href="#">Samples</a>
SN54ALS832AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS832AJ	<a href="#">Samples</a>
SN74ALS832ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS832A	<a href="#">Samples</a>
SN74ALS832AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS832AN	<a href="#">Samples</a>
SN74AS832BDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS832B	<a href="#">Samples</a>
SN74AS832BDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS832B	<a href="#">Samples</a>
SN74AS832BDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS832B	<a href="#">Samples</a>
SN74AS832BN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS832BN	<a href="#">Samples</a>
SN74AS832BNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS832BN	<a href="#">Samples</a>
SNJ54ALS832AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8414501RA SNJ54ALS832AJ	<a href="#">Samples</a>
SNJ54AS832BFBK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 88523012A SNJ54AS 832BFBK	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54ALS832A, SN54AS832B, SN74ALS832A, SN74AS832B :**

● Catalog: [SN74ALS832A](#), [SN74AS832B](#)

● Military: [SN54ALS832A](#), [SN54AS832B](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### TAPE AND REEL INFORMATION

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AS832BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1



## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AS832BDWR	SOIC	DW	20	2000	367.0	367.0	45.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



14/18 Pin Only  
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



4220724/A 05/2016

## NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

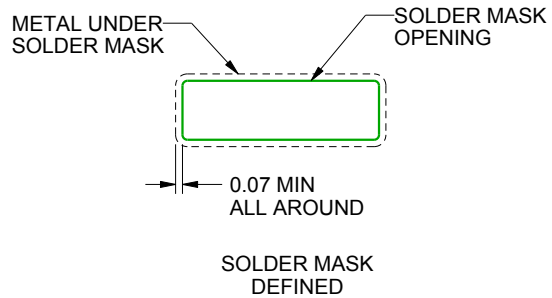
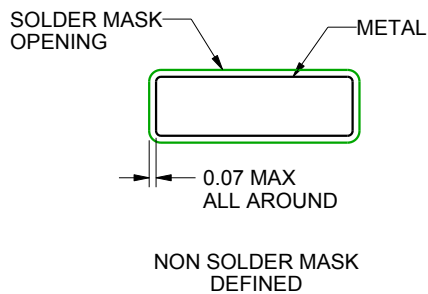
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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